

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F072VBT6	P01L*448XXXY	A	9998	2017-03-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	681.44	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	100	L Bend	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH- 7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	P01L*448XXY				6000000.0	0.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	9.639	mg	supplier	die	Silicon (Si)	7440-21-3		9.244	mg	959021	13565
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	2801	40
				supplier	metallization	Copper (Cu)	7440-50-8		0.134	mg	13902	197
				supplier	metallization	Cobalt (Co)	7440-48-4		0.025	mg	2594	37
				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	726	10
				supplier	metallization	Tungsten (W)	7440-33-7		0.015	mg	1556	22
				supplier	Passivation	Silicon Nitride	12033-89-5		0.018	mg	1867	26
				supplier	Passivation	Silicon Oxide	7631-86-9		0.169	mg	17533	248
				supplier	ALLOY	Copper (Cu)	7440-50-8		127.215	mg	958334	186686
				supplier	ALLOY	Chromium (Cr)	7440-47-3		0.385	mg	2900	565
LEADFRAME	M-011 Other inorganic materials	132.746	mg	supplier	ALLOY	Tin (Sn)	7440-31-5		0.320	mg	2411	470
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.256	mg	1928	376
				supplier	COATING	Nickel (Ni)	7440-02-0		4.431	mg	33380	6502
				supplier	COATING	Palladium (Pd)	7440-05-3		0.094	mg	708	138
				supplier	COATING	Gold (Au)	7440-57-5		0.045	mg	339	66
				supplier	GLUE	Silver(Ag)	7440-22-4		1.315	mg	700213	1930
				supplier	GLUE	Epoxy resin A	9003-36-5		0.047	mg	25027	69
				supplier	GLUE	Epoxy resin B	Proprietary		0.094	mg	50053	138
				supplier	GLUE	Allyl compound	Proprietary		0.150	mg	79872	220
				supplier	GLUE	Silica	Proprietary		0.141	mg	75080	207
BONDING WIRE	M-011 Other inorganic materials	1.534	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1.519	mg	990222	2229
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.015	mg	9778	22
				supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		53.599	mg	100276	78655
ENCAPSULATION	M-011 Other inorganic materials	534.884	mg	supplier	MOLDING COMPOUND	Silica (SiO3)	60676-86-0		449.126	mg	839559	-340916
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		2.680	mg	5014	3933
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		29.479	mg	55151	43260
FINISHING	M-011 Other inorganic materials	0.759	mg	supplier	CONNECTION COATING	Nickel (Ni)	7440-02-0		0.739	mg	973650	1084
				supplier	CONNECTION COATING	Palladium (Pd)	7440-05-3		0.016	mg	21080	23
				supplier	CONNECTION COATING	Gold (Au)	7440-57-5		0.004	mg	5270	6